

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 10/688,439
 Filing Date October 16, 2003
 Inventor Trung Tri Doan et al.
 Assignee Micron Technology, Inc.
 Group Art Unit 2813
 Examiner David S. Blum
 Attorney's Docket No. MI22-2416
 Customer No. 021567
 Title Methods of Forming Trench Isolation Regions

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

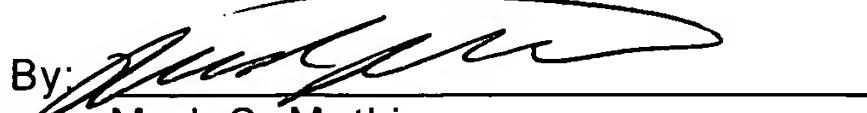
References - See Attached Form PTO-1449

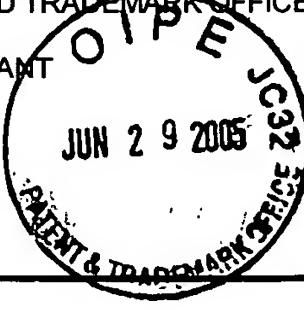
In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. Copies of the cited art references are attached. No admission is made regarding whether all the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed before the mailing of a first office action after the filing of a Request for Continued Examination. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

Respectfully submitted,

Dated: 6-29-05

By: 
 Mark S. Matkin
 Reg. No. 32,268

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. MI22-2416		SERIAL NO. 10/688,439	
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)			APPLICANT: Trung Tri Doan et al.			
					FILING DATE October 16, 2003		GROUP 2813	
U.S. PATENT DOCUMENTS								
*Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	6,013,583	01/2000	Ajmera et al.				
	AB							
	AC							
	AD							
	AE							
	AF							
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	AI							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AJ	0817251 A1	11.06.97	EPO (IBM)				
	AK	US2004/021156	07.07.03	PCT (Micron – Internat'l Search Rep.)				
	AL							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AM	Chen et al., <i>Excimer Laser-Induced Ti Silicidation to Eliminate the Fine-Line Effect for Integrated Circuit Device Fabrication</i> , J. ELECTROCHEM. SOC., Vol. 149, No. 11, pp. G609-G612 (2002).						
	AN	Nishiyama et al., <i>Agglomeration Resistant Self-Aligned Silicide Process Using N₂ Implantation Into TiSi₂</i> ,						
		JPN. J. APPL. PHYS., Vol. 36, Pt. 1, No. 6A, pp. 3639-3643 (June 1997).						
	AO	Wolf, Chapter 13: <i>Polycides and Salicides of TiSix, CoSi₂, and NiSi</i> , SILICON PROCESSING FOR THE VLSI ERA,						
		Vol. IV, pp. 603-604 (pre-2003).						
EXAMINER		DATE CONSIDERED						
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>								

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U.S. PATENT DOCUMENTS								
*Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	2001/0041250 A1	11/2001	Werkhoven et al.				
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	AH							
	AI							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
	AJ						Yes	No
	AK							
	AL							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AM							
	AN							
	AO							
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